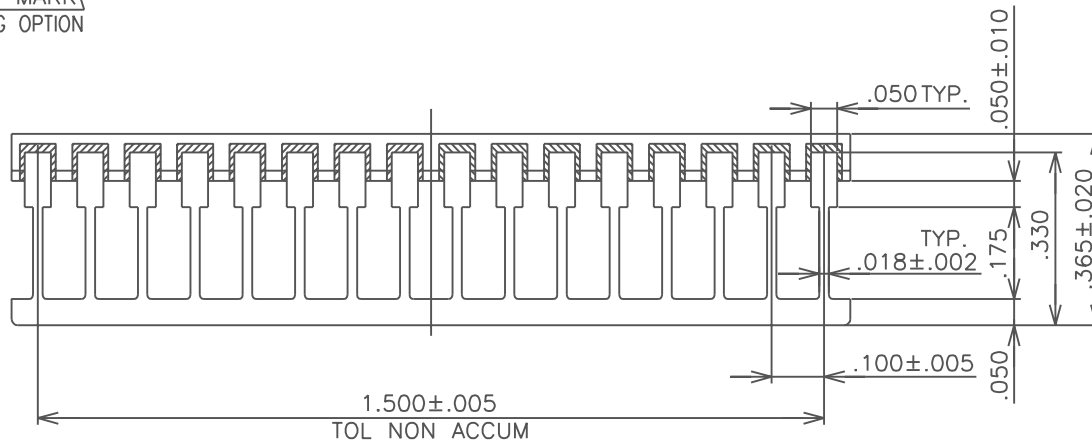


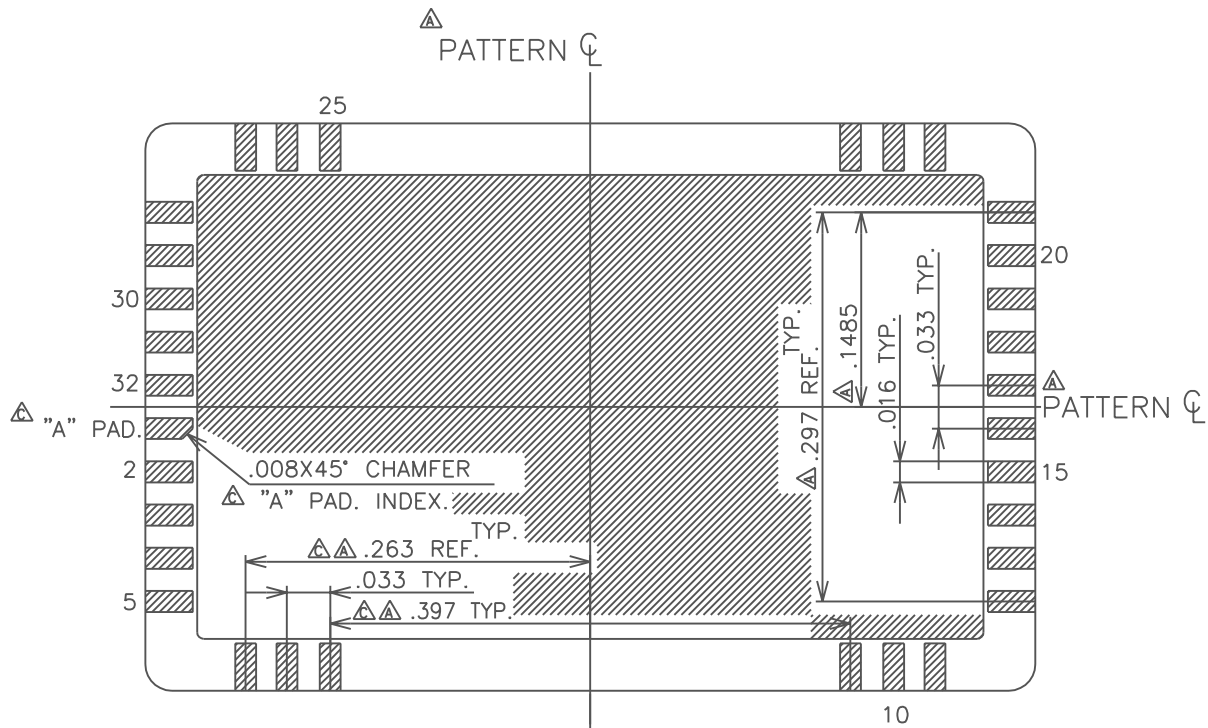
- NOTES
1. PLATING THICKNESS TO BE PER CUSTOMER'S SPECIFICATION.
 2. SEAL AREA TO BE METALLIZED.
 3. DIE ATTACH AREA TO BE METALLIZED.
 4. SEAL RING AND DIE ATTACH PAD TO BE FLOATING FROM ANY PINS.
 5. LEAD RESISTANCE : 0.60 OHM MAX.
 6. DIE ATTACH AREA TO BE ELECTRICALLY CONNECTED TO "A" PAD.



SB032T213-1				S=0 D=0
DRAWN	CHECKED	APPROVED	DATE	
K.I	K.O	M.M	AUG.19.'87	
DRAWING NO.				SHEET
KD-S87213-C				1/2

MODIFICATION	NAME						TOLERANCE	
	32 LEAD SIDE BRAZED PACKAGE						UNLESS OTHERWISE SPECIFIED	
	SCALE 4 / 1						±.005	
MATERIAL						THIRD ANGLE PROJECTION		
AS INDICATED								
△	REDRAWN. CHANGED: .680 → .679, .778 → .777, ADDED: NOTES.6	AUG.19.'87	K.I	K.O	M.M			
△	CHANGED: .551 → .600, .630 → .680, .728 → .778, REDRAWN.	JUL.14.'87	K.I	K.O	M.M			
CHANGED		DATE	DRAWN	CHECKED	APPROVED	KYOCERA CORPORATION KYOTO JAPAN		





BONDING PATTERN

MODIFICATION	1 → "A" PAD., PIN NO.1 INDEX. → "A" PAD. INDEX., ADDED: 2	AUG.19.'87	K.I	K.O	M.M	NAME 32 LEAD SIDE BRAZED PACKAGE	TOLERANCE UNLESS OTHERWISE SPECIFIED	DRAWN	CHECKED	APPROVED	DATE		
	△ REDRAWN.CHANGED: .238 REF. → .263 REF., .348 TYP. → .397 TYP.							K.I	K.O	M.M	AUG.19.'87		
	△ REDRAWN PATTERN ☺	JUL.14.'87	K.I	K.O	M.M			SCALE 10 / 1	MATERIAL				
	△ REDRAWN.CHANGED: .362 → .348 ADDED: .238 REF. .297 REF. .1485	APR.23.'87	K.I	K.O	M.M								
	CHANGED	DATE	DRAWN	CHECKED	APPROVED								
							THIRD ANGLE PROJECTION						
							KYOCERA CORPORATION KYOTO JAPAN	DRAWING NO.		SHEET			
								KD-S87213-C		2 / 2			